

SHENMAO Features Laser Soldering Paste at IPC APEX 2016

SHENMAO Features a new Sn-3.0Ag-0.5Cu Lead-Free Solder Paste **PF606-P133H** for laser soldering applications. Dispensed from syringes, it is developed for automatic laser soldering processes in the packaging and assembly of surface mount devices and microelectronics. Laser energy is applied at the precise location in a non-contact procedure to create high shear strength well-formed solder joints during the lower thermal stress process while reducing intermetallic formation. **PF606-P133H** solder paste produces minimal flux residue and no-splash or solder balling issues. It is well suited for high yield soldering of sensitive electronic components in manufacturing or repair of electronic devices that can-not tolerate conventional reflow-oven temperature.

PF606-P133H is approved by world leading electronic component manufacturers.

As the World's Major Solder Materials Provider, SHENMAO produces SMT Solder Paste, Wave Solder Bar, Solder Wire and Flux, Solder Preforms, Semiconductor Packaging Solder Spheres, Wafer Bumping Solder Paste, Dipping Flux and PV Ribbon.



BOOTH # 1721 www.ipcapexexpo.org/



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